

ALPHA[®] EF-8300

Low-Rosin, Pb-Free, Sn-Pb Capable Wave Flux

DESCRIPTION

ALPHA EF-8300 is a rosin-containing flux designed to provide the attributes of excellent solderability and reliability in general and high-density boards in both Lead-Free and eutectic tin/lead processes. It is designed to have low bridging on bottom side QFP's with 144-168 leads as well as superior performance in hole-fill and solderballing. Additionally, it provides good lead free solder joint cosmetics with an evenly spread, tack free residue.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

Features for Pb-Free:

- Good hole-fill demonstrated by >96% yield on 10 mil holes.
- Low bridging performance on connectors.
- Good micro-solder ball performance in Lead-Free applications
- Pin testable
- Specifically designed for use on Cu-OSP PCBs

Benefits:

- Excellent Lead-Free soldering performance on various board finishes.
- Evenly spread, tack free residue.
- Capable for high density as well as general purpose Lead-Free soldering processes.
- Can be used in Pb free or Sn/Pb processes

APPLICATION GUIDELINES

Preparation: To maintain consistent soldering performance and electrical reliability, it is important to begin the process with circuit boards and components that meet established requirements for solderability and ionic cleanliness. It is suggested that assemblers establish specifications on these items with their suppliers and that suppliers provide Certificates of

Analysis with shipments and/or assemblers perform incoming inspection. A common specification for the ionic cleanliness of incoming boards and components is 5µg/in² maximum, as measured by an Omegameter with heated solution.

Care should be taken in handling the circuit boards throughout the process. Boards should always be held at the edges. The use of clean, lint-free gloves is also recommended.

Conveyors, fingers and pallets should be cleaned. Alpha brand stencil cleaner is recommended for this process.

Flux Application: ALPHA EF-8300 can be applied by spray or foam. When spray fluxing, the uniformity of the coating can be visually checked by running a piece of cardboard over the spray fluxer or by processing a board-sized piece of tempered glass through the spray and then through the preheat section.

Operating Parameter	SAC 305 or low Ag SAC alloys	63/37 Sn/Pb
Amount of Flux Applied	Spray: 800 to 1200µg/in ² of solids/in ² for dual wave and 700 to 1000 µg/in ² of solids/in ² for single wave soldering	Spray: 800 to 1200µg/in ² of solids/in ² for dual wave and 600 to 900µg/in ² of solids/in ² for single wave soldering
Top-Side Preheat Temperature	80 to 110 °C	75 to 95 °C
Bottom side Preheat Temperature	0 to 40 °F (0 to 22 °C) vs. Top-Side	0 to 40°F (0 to 22°C) vs. Top-Side
Recommended Preheat Profile	Straight ramp to desired top-side temperature	Straight ramp to desired top-side temperature
Maximum Ramp Rate of Topside Temperature (to avoid component damage)	2 °C/second (3.5 °F/second) maximum	2 °C/second (3.5 °F/second) maximum
Conveyor Angle	5 to 8° (6° most common recommended by equipment manufacturers)	5 to 8° (6° most common recommended by equipment manufacturers)
Conveyor Speed	1.5 to 2.0 meters/minute for single wave, 1.8 to 2.2 meters/minute for dual wave. EF-8300 is capable of running at a slower conveyor speed to accommodate certain types of Lead Free wave soldering process	1.5 to 2.0 meters/minute for single wave, 1.8 to 2.2 meters/minute for dual wave

Operating Parameter	SAC 305 or low Ag SAC alloys	63/37 Sn/Pb
Contact Time in the Solder (includes Chip Wave and Primary Wave)	1.5 to 4.0 seconds (2½ to 3 seconds most common)	1.5 to 4.0 seconds (2½ to 3 seconds most common)
Solder Pot Temperature:	255 to 265 °C	240 to 250 °C
These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different. To optimize your process, it is recommended to perform a design experiment, optimizing the most important variables (amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation).		

Flux Solids Control: If rotary drum spray fluxing, the flux solids will need to be controlled via thinner addition. For measuring the solids content, Alpha's Flux Solids Control Kit #3, a digital titrator, is suggested. Request Alpha's Reference Bulletin for details on the kit and titration procedure. When operating a rotary drum fluxer continuously, the acid number should be checked every eight hours. Over time, debris and contaminants will accumulate in recirculating type flux applicators. For consistent soldering performance, dispose of spent flux every 40 hours of operation. After emptying the flux, the reservoir should be thoroughly cleaned with IPA.

Residue Removal: ALPHA EF-8300 is a no-clean flux and the residues are designed to be left on the board. If desired, flux residues can be removed with ALPHA 2110 saponifier cleaner and with other commercially available solvent cleaners and saponifier cleaners.

Touch-Up/Rework: Use of the ALPHA Cleanline Write Flux Applicator with ALPHA NR-205 flux and ALPHA Telecore™ Series cored solder is recommended for hand soldering applications.

TECHNICAL DATA

Physical Properties	Typical Values	Parameters/Test Method	Typical Values
Appearance	Clear, Pale Yellow Liquid	pH, 5% v/v aqueous solution	3.0
Solids Content, wt/wt, %	6.3	Recommended Thinner	ALPHA 425
Specific Gravity @ 25 °C (77 °C)	0.804 ± 0.003	Shelf Life (from Date of Mfg.)	360 days
Acid Number (mg KOH/g)	34.5 ± 2.5	IPC J-STD-004 Designation	ROM0
Flash Point (T.C.C.)	17 °C	Belcore SIR	PASS

CORROSION & ELECTRICAL TESTING – SAC305 ALLOY
Corrosion Testing

Test	Requirement for ROM0	Results
Silver Chromate Paper IPC-TM 650 Test Method 2.3.33	No detection of halide	PASS
Copper Mirror Tests IPC-TM 650 Test Method 2.6.32	<50% removal of copper	< 50 % removal (M)
Copper Corrosion Test IPC-TM 650 Test Method 2..3.15	No evidence of corrosion	No Evidence of Corrosion

J-STD-004 Surface Insulation Resistance

Test	Conditions	Requirements	Results
"Comb-Down" Un-cleaned	85 °C/85% RH, 7 days	> 1.0 x 10 ⁸ Ω	1.1 x 10 ¹⁰ Ω
"Comb-Up" Un-cleaned	85 °C/85% RH, 7 days	> 1.0 x 10 ⁸ Ω	2.4 x 10 ¹⁰ Ω
Control Boards	85 °C/85% RH, 7 days	> 1.0 x 10 ⁹ Ω	1.6 x 10 ¹⁰ Ω
IPC Test Condition (per J-STD-004A): -50V, measurement @ 100V/IPC B-24 board (0.4 mm lines, 0.5 mm spacing)			

Bellcore Surface Insulation Resistance

Test	Conditions	Requirements	Results
"Comb-Down" Un-cleaned	35 °C/85% RH, 4 days	> 1.0 x 10 ¹¹ Ω	2.4 x 10 ¹¹ Ω
"Comb-Up" Un-cleaned	35 °C/85% RH, 4 days	> 1.0 x 10 ¹¹ Ω	2.4 x 10 ¹¹ Ω
Control Boards	35 °C/85% RH, 4 days	> 2.0 x 10 ¹¹ Ω	5.0 x 10 ¹¹ Ω
Bellcore Test Condition (per GR 78-CORE, Issue 1: 48 Volts, measurement @ 100V/25 mil lines/50 mil spacing).			

Bellcore Electromigration

Test	SIR (Initial)	SIR (Final)	Requirement	Result	Visual Result
"Comb-Up" Un-cleaned	1.6 x 10 ¹¹ Ω	3.1 x 10 ¹¹ Ω	SIR (Initial) / SIR (Final) <10	Pass	Pass
"Comb-Down" Uncleaned	6.5 x 10 ⁹ Ω	2.1 x 10 ⁹ Ω	SIR (Initial) / SIR (Final) <10	Pass	Pass
Control	1.2 x 10 ¹¹ Ω	>1.0 x 10 ¹² Ω	Not applicable	N/A	N/A
Bellcore Test Condition (per GR 78-CORE, Issue 1): 65 °C/85% RH/500 Hours/10V, measurement @ 100V/IPC B-25B Pattern (12.5 mil lines, 12.5 mil spacing).					

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area or [link here](#).



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacDermidAlpha.com/assembly-solutions/knowledge-base.**

CONTACT INFORMATION

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

www.macdermidalpha.com

<p>North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.367.5460</p>	<p>Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400</p>	<p>Asia 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100</p>
--	--	---

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE . Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "(R)" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.